Nonpolar (Al, B, In, Ga)N Quantum Well Design
Tech ID: 10277 / UC Case 2003-529-0

BRIEF DESCRIPTION
A novel approach to designing high-performance nonpolar quantum wells.

BACKGROUND
Nitride-based optoelectronic devices currently utilize quantum well structures that are grown in polar directions. The polarization-induced electric fields that result from this growth orientation influence the structure's energy band profiles, which then effect its optical emission characteristics. The internal electric field tilts the energy band profiles and spatially separates the charge carriers, which reduces the oscillator strength of the electron-hole pair and ultimately reduces the recombination efficiency of the quantum well. Nonpolar nitride-based semiconductor crystals do not experience the effects of polarization-induced electric fields since the energy band profiles are flat. As a result, nonpolar quantum wells should exhibit improved recombination efficiency, as well as achieve more intense emission from thicker quantum wells.

DESCRIPTION
Scientists at the University of California have developed a novel approach to designing high-performance nonpolar quantum wells. This technique can be used to grow higher-emission structures by increasing the quantum well width.

ADVANTAGES
- Increased quantum well width in order to optimize emission in nonpolar nitride-based devices.

APPLICATIONS
- LED fabrication

This technology is available for a non-exclusive license. See below for a selection of the patents and patent applications related to this invention. Please inquire for full patent portfolio status.

PATENT STATUS

<table>
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<th>Country</th>
<th>Type</th>
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<tr>
<td>United States Of America</td>
<td>Issued Patent</td>
<td>9,893,236</td>
<td>02/13/2018</td>
<td>2003-529</td>
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ADDITIONAL TECHNOLOGIES BY THESE INVENTORS
- Method for Improved Surface of (Ga,Al,In,B)N Films on Nonpolar or Semipolar Substrates
- High Efficiency LED with Optimized Photonic Crystal Extractor
- Enhanced Optical Polarization of Nitride LEDs by Increased Indium Incorporation
- Flexible Arrays of MicroLEDs using the Photoelectrochemical (PEC) Liftoff Technique
- Vertical Cavity Surface-Emitting Lasers with Continuous Wave Operation
- Gallium-containing MicroLEDs for Displays
- Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-183)
- Defect Reduction in GaN films using in-situ SiNx Nanomask
- Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
Highly Efficient Blue-Violet III-Nitride Semipolar Laser Diodes
Hybrid Growth Method for Improved III-Nitride Tunnel Junction Devices
Low Temperature Deposition of Magnesium Doped Nitride Films
Transparent Mirrorless (TML) LEDs
Laser Diode With Tunnel Junction Contact Surface Grating
Optimization of Laser Bar Orientation for Nonpolar Laser Diodes
High Efficiency Semipolar AlGaN-Cladding-Free Laser Diodes
Method for Enhancing Growth of Semipolar Nitride Devices
III-Nitride Tunnel Junction with Modified Interface
Improved Fabrication of Nonpolar InGaN Thin Films, Heterostructures, and Devices
Growth of High-Quality, Thick, Non-Polar M-Plane GaN Films
Increased Light Extraction with Multistep Deposition of ZnO on GaN
Selective-Area Mesoporous Semiconductors And Devices For Optoelectronic And Photonic Applications
High-Efficiency, Mirrorless Non-Polar and Semi-Polar Light Emitting Devices
Near-Infrared, Flip-Chip, TCO-Clad, InGaN Quantum Dot Laser Diode
Incorporating Temperature-Sensitive Layers in III-N Devices
Oxyfluoride Phosphors for Use in White Light LEDs
Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
(In,Ga,A)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
MOCVD Growth of Planar Non-Polar M-Plane Gallium Nitride
Reduced Dislocation Density of Non-Polar GaN Grown by Hydride Vapor Phase Epitaxy
Heterogeneously Integrated GaN on Si Photonic Integrated Circuits
(Al, In,Ga, B)N Device Structures
Reduction in Leakage Current and Increase in Efficiency of III-Nitride MicroLEDs
Methods for Fabricating III-Nitride Tunnel Junction Devices
Formation of Transparent Integrated MicroLED Displays
Low-Droop LED Structure on GaN Semi-polar Substrates
Contact Architectures for Tunnel Junction Devices
Semi-polar LED/LD Devices on Relaxed Template with Misfit Dislocation at Hetero-interface
Photoelectrochemical Etching Of P-Type Semiconductor Heterostructures
Semi-polar-Based Yellow, Green, Blue LEDs with Improved Performance
Growth of Semipolar III-V Nitride Films with Lower Defect Density
III-Nitride Tunnel Junction LED with High Wall Plug Efficiency
Improved Manufacturing of Solid State Lasers via Patterned of Photonic Crystals
Solid Solution Phosphors for Use in Solid State White Lighting Applications
Tunable White Light Based on Polarization-Sensitive LEDs
Cleaved Facet Edge-Emitting Laser Diodes Grown on Semipolar GaN
Growth of High-Performance M-plane GaN Optical Devices
Packaging Technique for the Fabrication of Polarized Light Emitting Diodes
Improved Anisotropic Strain Control in Semipolar Nitride Devices
High Light Extraction Efficiency III-Nitride LED
III-V Nitride Device Structures on Patterned Substrates
Hexagonal Wurtzite Type Epitaxial Layer with a Low Alkali-Metal Concentration
Method for Increasing GaN Substrate Area in Nitride Devices
Growth of Planar, Non-Polar, A-Plane GaN by Hydride Vapor Phase Epitaxy
Single or Multi-Color High Efficiency LED by Growth Over a Patterned Substrate
GaN-Based Thermoelectric Device for Micro-Power Generation
Limiting Strain-Relaxation in III-Nitride Heterostructures by Substrate Patternning
LED Device Structures with Minimized Light Re-Absorption
Improved Light Extraction with Geometrically Tuned LED Arrays
Growth of Planar Semi-Polar Gallium Nitride
UV Optoelectronic Devices Based on Nonpolar and Semi-polar AlInN and AlInGaN Alloys
Defect Reduction of Non-Polar and Semi-Polar III-Nitrides
Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-150)
Suppression of Defect Formation and Increase in Critical Thickness by Silicon Doping
Wafer Bonding for Embedding Active Regions with Relaxed Nanostructures
Enhancing Growth of Semipolar (Al,Ga,Na,B)N Films via MOCVD